



DIN signal female connector



General information

Design	IEC 60603-2	types: B, 2B, 3B, C, 2C, 3C, M
No. of contacts	max. 96	
Contact spacing	2,54 mm	
Test voltage	1000V	
Contact resistance	≤ 20 mOhm	
Insulation resistance	≥ 10 ¹² Ohm	
Working current	2 A@20°C (for signal contacts)	
Temperature range	-55°C ... +125°C -40°C ... +105°C	for press-in connectors (due to limit ations of PCB-material)
Termination technology	press-in, solder pins	
Clearance & creepage distance	min. 1,2 mm each	
Insertion and withdrawal force	16pol. ≤ 15N 30pol. ≤ 30N 48pol. ≤ 45N	20pol. ≤ 20N 32pol. ≤ 30N 64pol. ≤ 60N 96pol. ≤ 90N
Mating cycles	- PL1 acc. to IEC 60 603-2 => - PL2 acc. to IEC 60 603-2 => - PL3 acc. to IEC 60 603-2 =>	500 mating cycles 400 mating cycles 50 mating cycles
UL file	E102079	
RoHS - compliant	Yes	
Leadfree	Yes	
Hot plugging	No	

Insulator material

Material	PBT (thermoplastics, glass fiber reinforcement 30%)
Color	RAL 7032 (grey)
UL classification	UL 94-V0
Material group acc. IEC 60664-1	IIIa (175 ≤ CTI < 400)
NFF classification	I3, F4

Contact material

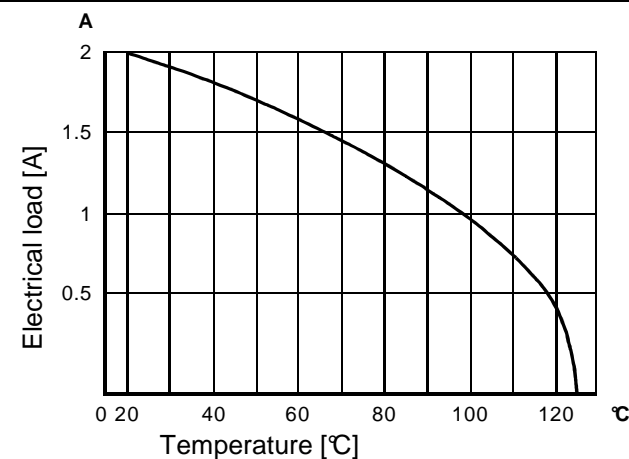
Contact material	Copper alloy
Plating termination zone	Sn over Ni for solder, Ni for press-in
Plating contact zone	Au over PdNi over Ni (Au over Ni for PL3)

Derating diagram acc. to IEC 60512-5 (Current carrying capacity)

The current carrying capacity is limited by maximum temperature of materials for inserts and contacts including terminals.

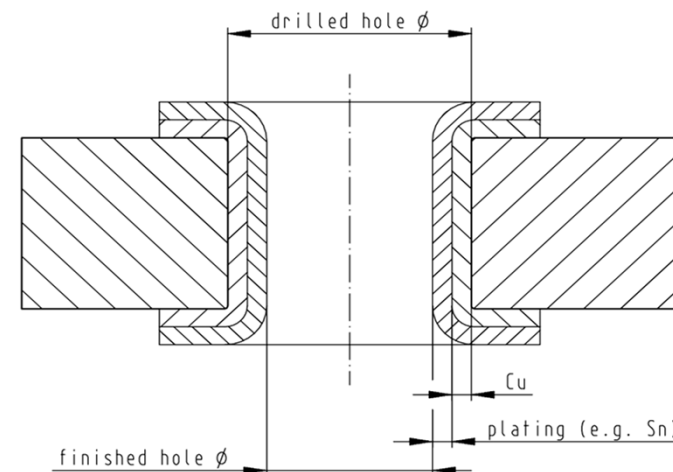
The current capacity curve is valid for continuous, non interrupted current loaded contacts of connectors when simultaneous power on all contacts is given, without exceeding the maximum temperature.

Control and test procedures according to DIN IEC 60512-5



Recommended configuration of plated through holes for press-in termination

In addition to the hot-air-level (HAL), other PCB surfaces are getting more important. Due to their different properties - such as mechanical strength and coefficient of friction - we recommend the following configuration of PCB through holes.



Tin plated PCB (HAL) acc. to EN 60352-5	Drilled hole Ø	1,15±0,025 mm
	Cu	min. 25 µm
	Sn	max. 15 µm
Chemical tin plated PCB	plated hole Ø	0,94 – 1,09 mm
	Drilled hole Ø	1,15±0,025 mm
	Cu	min. 25 µm
Gold /Nickel plated PCB	Sn	min. 0,8 µm
	plated hole Ø	1,00 – 1,10 mm
	Drilled hole Ø	1,15±0,025 mm
	Cu	min. 25 µm
	Ni	3-7 µm
Silver plated PCB	Au	0,05-0,12 µm
	plated hole Ø	1,00 – 1,10 mm
	Drilled hole Ø	1,15±0,025 mm
	Cu	min. 25 µm
	Ag	0,1 – 0,3 µm
Copper plated PCB (OSP)	plated hole Ø	1,00 – 1,10 mm
	Drilled hole Ø	1,15±0,025 mm
	Cu	min. 25 µm

Assembly instructions

It is highly recommended to use HARTING press-in tools to ensure a reliable press-in process. Please refer to the catalogue for tools, machines and further information about the press-in process.

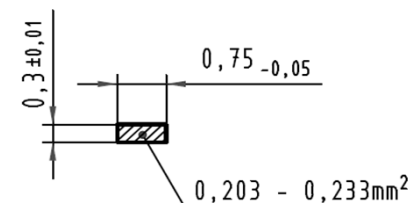
Soldering instructions

The connectors should be protected when being soldered in a dip, flow or film soldering baths. Otherwise, they might become contaminated as a result of soldering operations or deformed as a result of overheating.

(1) For prototypes and short runs protect the connectors with an industrial adhesive tape, e.g. Tesaband 4331 (www.tesa.de). Cover the underside of the connector moulding and the adjacent parts of the pcb as well as the open sides of the connector. This will prevent heat and gases of the soldering apparatus from damaging the connector. About 140 + 5 mm of the tape should suffice.

(2) For large series a jig is recommended. Its protective cover with a fast action mechanical locking device shields the connectors from gas and heat generated by the soldering apparatus. As an additional protection a foil can be used for covering the parts that should not be soldered.

Cross section of solder terminations



				Date	Name		Technical data sheet
			Detail.	11/08/11	mte		DIN signal female connector
			Inspec.	11/08/11	TD		
EC01482			Stand.				
Mod.	Date	Name	HARTING Electronics GmbH & Co. KG				DS 09 03 210 00 01